



Product Change Notification: MFOL-29XUOF620

Date:

30-Jun-2026

Product Category:

CAN Controller

Notification Subject:

CCB 8015 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material, MC27 as a new mold compound material, and EP27 as a new die attach material for MCP2515T-I/STRB4, MCP2515T-E/STRB2, MCP2515-I/STRB2, MCP2515-E/STRB4, MCP2515T-E/ST, MCP2515-E/ST, MCP2515-E/STRB2, MCP2515T-I/STRB2, MCP2515T-I/ST, MCP2515-I/STRB4, MCP2515T-E/STRB4, MCP2515-I/ST, MCP2515-E/STVAO, MCP2515T-E/STVAO, MCP2515-I/STVAO, and MCP2515T-I/STVAO catalog part numbers (CPN) available in 20L TSSOP (4.4mm) packages at ANAP assembly site.

Affected CPNs:

[MFOL-29XUOF620_Affected_CPN_06302026.pdf](#)

[MFOL-29XUOF620_Affected_CPN_06302026.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material, MC27 as a new mold compound material, and EP27 as a new die attach material for MCP2515T-I/STRB4, MCP2515T-E/STRB2, MCP2515-I/STRB2, MCP2515-E/STRB4, MCP2515T-E/ST, MCP2515-E/ST, MCP2515-E/STRB2, MCP2515T-I/STRB2, MCP2515T-I/ST, MCP2515-I/STRB4, MCP2515T-E/STRB4, MCP2515-I/ST, MCP2515-E/STVAO, MCP2515T-E/STVAO, MCP2515-I/STVAO, and MCP2515T-I/STVAO catalog part numbers (CPN) available in 20L TSSOP (4.4mm) packages at ANAP assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change	
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			Change (Yes/No)
Assembly Site	Amkor Technology Philippine (P1/P2), Inc. (ANAP)	Amkor Technology Philippine (P1/P2), Inc. (ANAP)	No
Wire Material	Au	CuPdAu	Yes
Die Attach Material	8290 (PFAS)	EP27 (PFAS-Free)	Yes
Molding Compound Material	G700K	MC27	Yes
Lead-Frame Material	C194	C194	No
Lead-Frame DAP Surface Prep	Ring Ag (Bare Cu, Ag on lead)	Two-sided Roughened Ring Ag	Yes
Lead-Frame Design	See Pre and Post Change Summary attachment for comparison.		

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) as a new bond wire material, MC27 as a new mold compound material, and EP27 as a new die attach material standardize the use of PFAS free material at ANAP assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date: 30 November 2026 (date code: 2649)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	February 2026				>	June 2026					>	November 2026				
Work Week	06	07	08	09		23	24	25	26	27		45	46	47	48	49
Initial PCN Issue Date	x															
Qual Report Availability										x						

Final PCN Issue Date										X						
Estimated Implementation Date																X

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: February 02, 2026: Issued initial notification.
June 30, 2026: Issued final notification. Attached the qualification report. Provided estimated first ship date to be on November 30, 2026.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_MFOL-29XUOF620_Pre and Post Change Summary.pdf
PFAS Elimination and Die Attach_Explanation.pdf
PCN_MFOL-29XUOF620 Qual Report.pdf

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN):

MCP2515-I/ST

MCP2515T-E/STRB4

MCP2515T-I/STRB4

MCP2515-I/STRB4

MCP2515T-I/ST

MCP2515T-I/STRB2

MCP2515-E/STRB2

MCP2515-E/ST

MCP2515T-E/ST

MCP2515-E/STRB4

MCP2515-I/STRB2

MCP2515T-E/STRB2

MCP2515T-I/STVAO

MCP2515-E/STVAO

MCP2515-I/STVAO

MCP2515T-E/STVAO



Qualification Report Summary

RELIABILITY LABORATORY

PCN #: MFOL-29XUOF620

Date: June 18, 2026

Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material, MC27 as a new mold compound material, and EP27 as a new die attach material for MCP2515T-I/STRB4, MCP2515T-E/STRB2, MCP2515-I/STRB2, MCP2515-E/STRB4, MCP2515T-E/ST, MCP2515-E/ST, MCP2515-E/STRB2, MCP2515T-I/STRB2, MCP2515T-I/ST, MCP2515-I/STRB4, MCP2515T-E/STRB4, MCP2515-I/ST, MCP2515-E/STVAO, MCP2515T-E/STVAO, MCP2515-I/STVAO, and MCP2515T-I/STVAO catalog part numbers (CPN) available in 20L TSSOP (4.4mm) packages at ANAP assembly site.



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PACKAGE QUALIFICATION REPORT

Purpose:

Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material, MC27 as a new mold compound material, and EP27 as a new die attach material for MCP2515T-I/STRB4, MCP2515T-E/STRB2, MCP2515-I/STRB2, MCP2515-E/STRB4, MCP2515T-E/ST, MCP2515-E/ST, MCP2515-E/STRB2, MCP2515T-I/STRB2, MCP2515T-I/ST, MCP2515-I/STRB4, MCP2515T-E/STRB4, MCP2515-I/ST, MCP2515-E/STVAO, MCP2515T-E/STVAO, MCP2515-I/STVAO, and MCP2515T-I/STVAO catalog part numbers (CPN) available in 20L TSSOP (4.4mm) packages at ANAP assembly site.

CN: E000297241
QUAL ID: R2600430 Rev. A
MP CODE: CEAJ1YG2XVA1
Part No.: MCP2515T-E/STVAO
Bonding No.: BD-004060 rev.01
CCB No.: 8015

Lead-Frame

Paddle Size: 118x165 mil
Material: C194
DAP Surface Prep: Two sided Roughened Ring Ag
Process: Stamp
Lead Lock: Yes
Part Number: 101386869
Plating Composition: Matte Tin
Treatment: Roughening
Strip Size XDLF
Strip Density XDLF

Bond wire

Wire: CuPdAu

Die Attach Material

Epoxy: EP27
Conductive: Yes

Mold Compound

Mold Compound: MC27

Package

Type: TSSOP
Package Size: 20L, 4.4mm width

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PACKAGE QUALIFICATION REPORT

Manufacturing Information

Assembly Lot No.
ANAP265000051.000
ANAP265000052.000
ANAP265000053.000

Conclusion:

Qualification of CEAJ1 mask / MCP2515T-E/STVAO product / CuPdAu wire in 20L TSSOP 4.4mm package at ANAP site is qualified for MSL1 at 260°C as per JEDEC J-STD-020 standard and is passed in accordance to Specified JEDEC and Mil Standards



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PACKAGE QUALIFICATION REPORT

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result
Moisture Soak Precondition Prior to Stresses	MSL1: 150°C 24 hours Bake, 168 hours Moisture Soak at 85°C/85%RH, 3x Reflow at 260°C Electrical Test: 25°C, 85°C, and 125°C Tester: J750	JESD22-A113, JEDEC J-STD-020	231 units each lot / 3 lots	Electrical Results: 0/231, 0/231, 0/231; Results: 0/45, 0/45, 0/45	Pass

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result
High Temp Storage	175°C / 500 hours Electrical Test: 25°C, 85°C, and 125°C Tester: J750	JESD22-A103	45 units each lot / 3 lots	Electrical Results: 0/45, 0/45, 0/45; WBS: 0/3, 0/3, 0/3; : 0/1, 0/1, 0/1	Pass



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PACKAGE QUALIFICATION REPORT

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result
Temperature Cycling	-55°C / +150°C Air to Air / 1000 Cycles Electrical Test: 25°C, 85°C, and 125°C Tester: J750	JESD22-A104	77 units each lot / 3 lots	Electrical Results: 0/77, 0/77, 0/77; Results: 0/11, 0/11, 0/11; WBP: 0/3, 0/3, 0/3; WBS: 0/3, 0/3, 0/3; IPA Cross Section: 0/1, 0/1, 0/1	Pass

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result
Biased HAST	+130°C / 85%RH / 96 hours / Bias Voltage: 5.5V Electrical Test: 25°C, 85°C, and 125°C Tester: J750	JESD22-A110	77 units each lot / 3 lots	Electrical Results: 0/77, 0/77, 0/77; Results: 0/11, 0/11, 0/11; WBP: 0/3, 0/3, 0/3; WBS: 0/3, 0/3, 0/3; IPA Cross Section: 0/1, 0/1, 0/1	Pass

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result
Unbiased HAST	+130°C / 85%RH / 96 hours Electrical Test: 25°C Tester: J750	JESD22-A118	77 units each lot / 3 lots	Electrical Results: 0/77, 0/77, 0/77	Pass

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result
Solderability (0 Hr) Method 1: Dip and Look	Pb-free 8 hours Steam age. Dip at 245°C, 100% leads >95% lead coverage	J-STD-002 / JESD22B-102	22 units / 1 lot	0/22	Pass



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PACKAGE QUALIFICATION REPORT

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result
Physical Dimension (0Hr)	Within package diagram dimension	JESD22 B100 and B108	10 units each lot / 3 lots	0/30	Pass

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result
Wire Pull	Bond Strength Data Assembly	Mil. Std. 883-2011	5 units / 1 lot	0/5	Pass

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result
Bond Shear	Bond Strength Data Assembly	CDF-AEC-Q100 -001	5 units / 1 lot	0/5	Pass

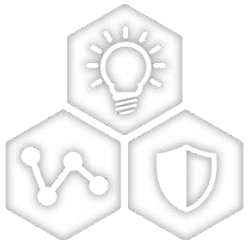
CCB 8015

Pre and Post Change Summary

PCN #: MFOL-29XUOF620

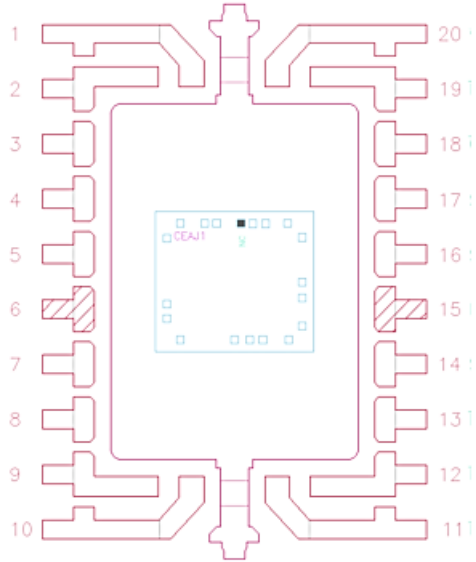
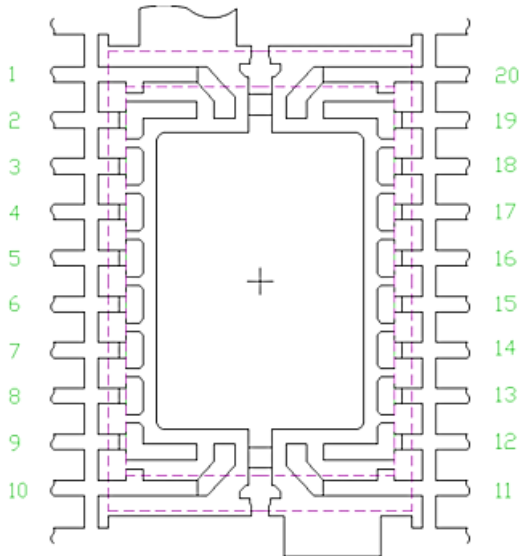


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Pre and Post Change Summary Comparison

PRE CHANGE	POST CHANGE								
 The diagram shows a square lead frame with 20 pins. The pins are numbered 1 through 10 on the left and 11 through 20 on the right. A central square area contains a small square with the text 'CEA1' and a small square with a cross. The lead frame is outlined in red.	 The diagram shows a square lead frame with 20 pins. The pins are numbered 1 through 10 on the left and 11 through 20 on the right. A central square area contains a small square with a cross. The lead frame is outlined in green. Dashed lines indicate a change in the lead frame structure.								
<table><tr><td>Lead Frame Material</td><td>C194</td></tr><tr><td>Lead Frame DAP Surface Prep</td><td>Ring Ag (Bare Cu, Ag on lead)</td></tr></table>	Lead Frame Material	C194	Lead Frame DAP Surface Prep	Ring Ag (Bare Cu, Ag on lead)	<table><tr><td>Lead Frame Material</td><td>C194</td></tr><tr><td>Lead Frame DAP Surface Prep</td><td>Two-sided Roughened Ring Ag</td></tr></table>	Lead Frame Material	C194	Lead Frame DAP Surface Prep	Two-sided Roughened Ring Ag
Lead Frame Material	C194								
Lead Frame DAP Surface Prep	Ring Ag (Bare Cu, Ag on lead)								
Lead Frame Material	C194								
Lead Frame DAP Surface Prep	Two-sided Roughened Ring Ag								

Note: *Not for scale

Eliminating PFAS from Microchip ICs



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Microchip
August 2025

Eliminating PFAS from MCHP ICs

- **What is PFAS**
- **Microchip's Environmental Stewardship**
- **Microchip Products with PFAS**
- **Time Frame to PFAS-Free Die Attach**
- **What is Die Attach**
- **Will clients be required to switch to PFAS free products**
- **Risk Assessment**

What is PFAS: Poly(Per) FluoroAlkyL Substances (**PFAS**)

Poly(Per) FluoroAlkyL Substances (PFAS)

- There may be 12,000 or more PFAS chemicals that are used in small amounts in many different items
 - PFAS can be in the product itself.
 - PFAS can also be used to manufacture products while not in the product itself

PFAS is the new “buzzword” throughout many industries

- Often nicknamed “forever chemicals” because once released into the environment, it never degrades and will accumulate over time
- As PFAS accumulates in the environment over long periods of time, there can be increasing toxicity and polluting effects
- Therefore, government agencies around the globe are considering legislation toward removal of PFAS although PFAS legislations are not fully defined yet

Microchip's Environmental Stewardship

Although very few laws have been enacted regarding PFAS to date, there is a rapidly growing movement among governments around the world to eliminate PFAS

- Initial legislation has targeted on clothing and food products
- Additional legislation and their timings continue to evolving

Companies such as Microchip, which are committed to addressing contaminants in water, air, food, and living organisms, are proactively working to remove PFAS even in the absence of specific legal requirements.

Microchip's suppliers are also taking proactive steps to eliminate PFAS chemicals from the materials they provide to Microchip.

Microchip believes it is prudent to take immediate action toward offering PFAS-free products to all clients, regardless of application, industry, country, or current regulatory requirements.

Achieving “PFAS-Free” status may serve as a competitive advantage for both Microchip and its clients.

Microchip products with PFAS

The primary material in Microchip products containing PFAS is known as die attach. PFAS-free die attach is not new to either Microchip or the industry; in fact, Microchip has shipped hundreds of millions of units utilizing PFAS-free die attach.

Both PFAS and PFAS-free die attach materials are currently in use because PFAS was not previously identified as a substance of concern.

The change announced in this Product Change Notification (PCN) for Microchip-owned factories involves transitioning to the same PFAS-free die attach that has already been qualified and used in other products.

Time Frame to PFAS-Free Die Attach

Qualification of products assembled at Microchip-owned factories has been completed.

While inventory containing PFAS die attach will continue to be shipped, the implementation of PFAS-free die attach in the assembly process is scheduled to begin as early as September 3, 2025.

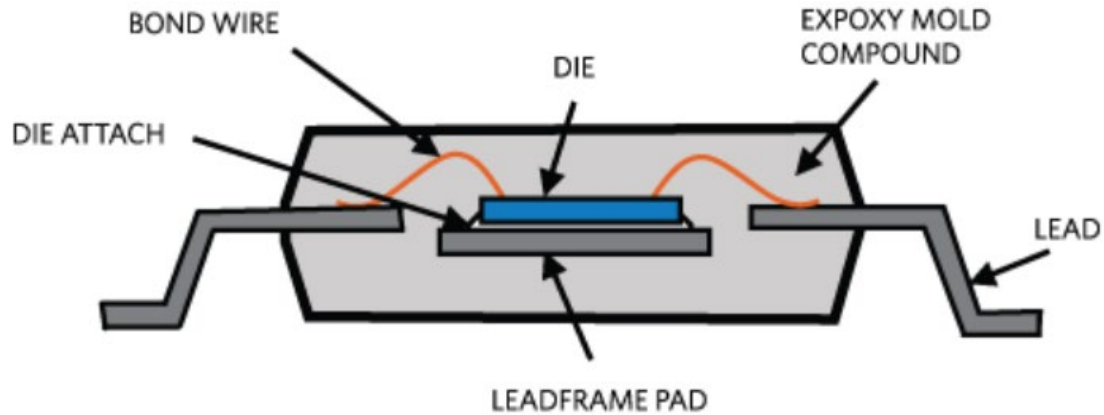
Microchip will consume all existing inventory and die attach, so the exact implementation date will depend on when current inventories are depleted.

- For PPAP clients IMDS/CAMDS material content declarations will be updated.

Schedules for assembly locations not owned by Microchip (subcontractors or "subcons") are currently under review. We anticipate a similar mix of products already utilizing both PFAS and PFAS-free die attach at these locations.

Product Change Notifications (PCNs) announcing die attach changes at subcontractor sites will be issued once schedules are finalized. We expect these timelines to be similar to those for our internal factories.

What is die attach



A thin layer of epoxy between the silicon die and copper pad portion of the lead frame.

- Holds the die in place during the wire bond and mold encapsulation processes
- The bottom of the die has no transistors or active circuits.
- The interface is identical regardless of device type, fab location, technology node, wire material etc.
- **Therefore, allows extremely broad range of products to be grouped into a single qualification.**

Will Clients be required to switch to PFAS-Free Products

The timeline for legislation to eliminate PFAS chemicals remains uncertain; however, regulatory action is anticipated.

Suppliers of PFAS chemicals and raw materials containing PFAS are already announcing end-of-life plans in advance of any formal legislation.

It is expected that suppliers will discontinue offering die attach materials containing PFAS within the next two years, regardless of when government regulations take effect.

While Microchip is committed to providing as much transition time as possible for our clients, we strongly encourage you to begin planning now to avoid potential supply interruptions.

Risk Assessment:



Microchip does not anticipate that this change will impact our clients for the following reasons:

- Microchip has been using PFAS-free die attach material for several years.
- We have shipped hundreds of millions of units utilizing this material without incident.
- Die Attach is not application relevant.

Given these factors, Microchip believes there is minimal cause for concern regarding this change, and additional client qualifications would be redundant and time-consuming. However, if you have any questions that are not addressed in the PCN or this presentation, please do not hesitate to contact us.

